

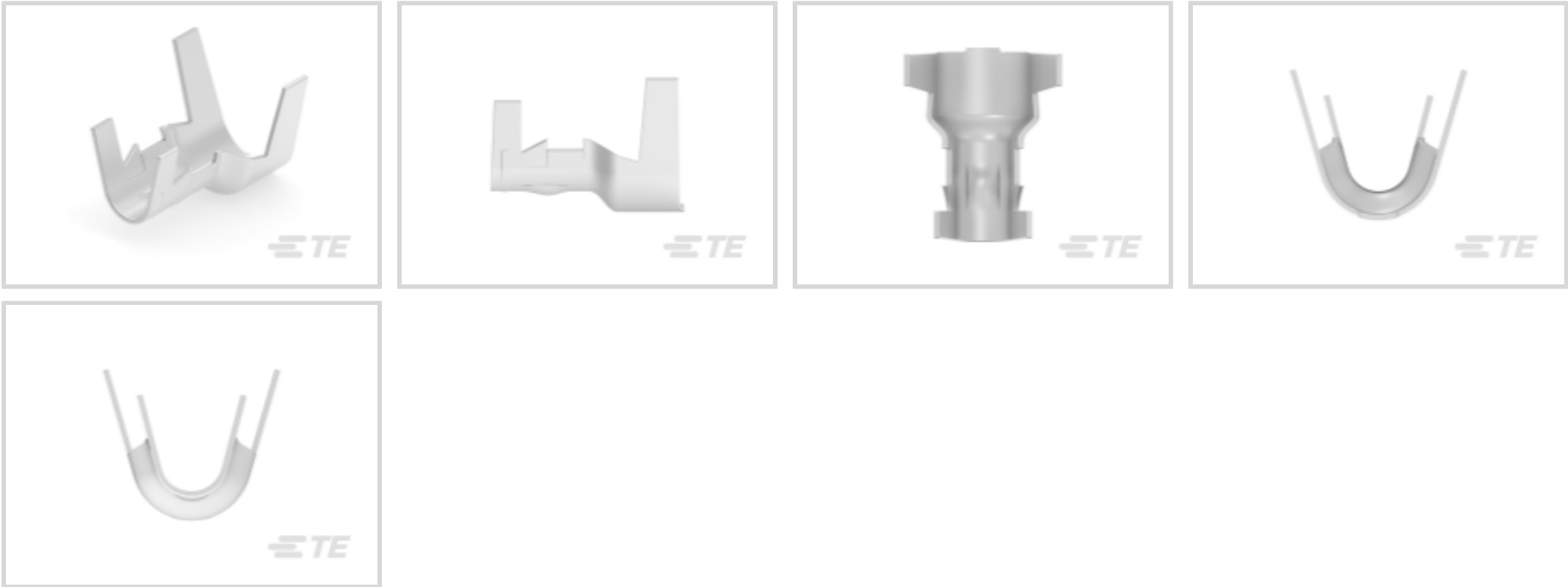


AMP-IN

TE Internal #: 2393237-1
Receptacle, 3.49 mm [.138 – .142 in] PCB Hole, 12 AWG, 13.29 – 21.14 mm² Wire, Through Hole - Solder, Tin Plating, Reel, PCB Terminals

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Terminals & Splices > PCB Terminals



PCB Terminal Type: **Receptacle**
PCB Thickness (Recommended): **1.6 mm [.063 in]**
PCB Hole Diameter: **3.49 mm [.138 – .142 in]**
Profile Height from PCB: **4.7 mm [.185 in]**
Compatible Insulation Diameter (Max): **4.2 mm [.165 in]**

Features

Product Type Features

Terminal Features	Stud Hole
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Contact Features

Contact Underplating Material Thickness	.5 µm[19.68 µin]
Contact Mating Area Plating Material Thickness	.8 µm[31.5 µin]
PCB Terminal Type	Receptacle
Terminal Plating Material	Tin
Contact Underplating Material	Brass
Terminal Size	Miniature
Terminal Orientation	Straight

Termination Features

Termination Method to PCB	Through Hole - Solder
Product Terminates To	Printed Circuit Board

Dimensions

Extension Below Board	2.75 mm[.108 in]
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PCB Thickness (Recommended)	1.6 mm[.063 in]
PCB Hole Diameter	3.49 mm[.138 – .142 in]
Profile Height from PCB	4.7 mm[.185 in]
Compatible Insulation Diameter (Max)	4.2 mm[.165 in]
Compatible Insulation Diameter Range	4. – 4.2 mm[.157 – .165 in]
Wire Size	13.29 – 21.14 mm²

Usage Conditions

Operating Temperature Range	-40 – 105 °C[-40 – 221 °F]
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Industry Standards

Compatible With Agency/Standards Products	UL
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Packaging Features

Packaging Method	Reel
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Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>



Compatible Parts



Documents

Product Drawings

MINI AMP-IN BOARD-IN CONTACT, 12AWG

English

CAD Files

Customer View Model

ENG_CVM_CVM_2393237-1_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2393237-1_A.3d_stp.zip

English

Customer View Model

ENG_CVM_CVM_2393237-1_A.3d_igs.zip

English

3D PDF

3D

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Application Specification

English